

GENERAL DESCRIPTION

Passivated guaranteed commutation triacs in a plastic envelope intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

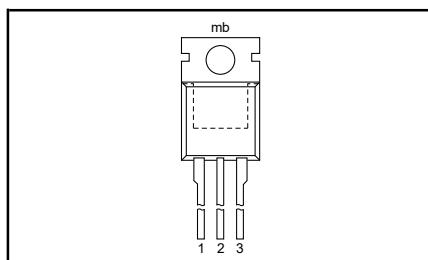
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
	BTA212-	600D	
	BTA212-	600E	
	BTA212-	600F	
V_{DRM}	Repetitive peak off-state voltages	600	V
$I_{T(RMS)}$	RMS on-state current	12	A
I_{TSM}	Non-repetitive peak on-state current	95	A

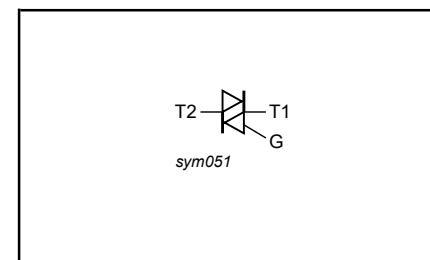
PINNING - TO220AB

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
tab	main terminal 2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DRM}	Repetitive peak off-state voltages		-	600 ¹	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 99^\circ C$	-	12	A
I_{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25^\circ C$ prior to surge $t = 20$ ms $t = 16.7$ ms $t = 10$ ms $I_{TM} = 20$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/ μ s	-	95 105 45 100	A A A ² s A/ μ s
I^2t dI_T/dt	I^2t for fusing Repetitive rate of rise of on-state current after triggering		-	2	A
I_{GM} P_{GM} $P_{G(AV)}$	Peak gate current Peak gate power Average gate power	over any 20 ms period	-	5 0.5	W W
T_{stg} T_j	Storage temperature Operating junction temperature		-40	150 125	°C °C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\cdot mb}$	Thermal resistance junction to mounting base	full cycle	-	-	1.5	K/W
$R_{th\ j\cdot a}$	Thermal resistance junction to ambient	half cycle in free air	-	60	2.0	K/W

STATIC CHARACTERISTICS

$T_j = 25^\circ C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
I_{GT}	Gate trigger current ²	BTA212- $V_D = 12 V; I_T = 0.1 A$ T2+ G+ T2+ G- T2- G-	-	...D	...E	...F	mA
I_L	Latching current	$V_D = 12 V; I_{GT} = 0.1 A$ T2+ G+ T2+ G- T2- G-	-	5	10	25	mA
I_H	Holding current	$V_D = 12 V; I_{GT} = 0.1 A$	-	15	20	25	mA
V_T	On-state voltage	$I_T = 17 A$	-	25	30	40	mA
V_{GT}	Gate trigger voltage	$V_D = 12 V; I_T = 0.1 A$ $V_D = 400 V; I_T = 0.1 A; T_j = 125^\circ C$	0.25	1.6	1.5	-	V
I_D	Off-state leakage current	$V_D = V_{DRM(max)}; T_j = 125^\circ C$	-	25	30	40	mA
				0.5			mA

DYNAMIC CHARACTERISTICS

$T_j = 25^\circ C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.			MAX.	UNIT
dV_D/dt	Critical rate of rise of off-state voltage	BTA212- $V_{DM} = 67\% V_{DRM(max)}$; $T_j = 110^\circ C$; exponential waveform; gate open circuit	30	60	70	-	V/μs
dl_{com}/dt	Critical rate of change of commutating current	$V_{DM} = 400 V; T_j = 125^\circ C$; $I_{T(RMS)} = 12 A$; $dV_{com}/dt = 10 V/\mu s$; gate open circuit	1.0	8	21	-	A/ms
dl_{com}/dt	Critical rate of change of commutating current	$V_{DM} = 400 V; T_j = 125^\circ C$; $I_{T(RMS)} = 12 A$; $dV_{com}/dt = 0.1 V/\mu s$; gate open circuit	3.5	16	32	-	A/ms

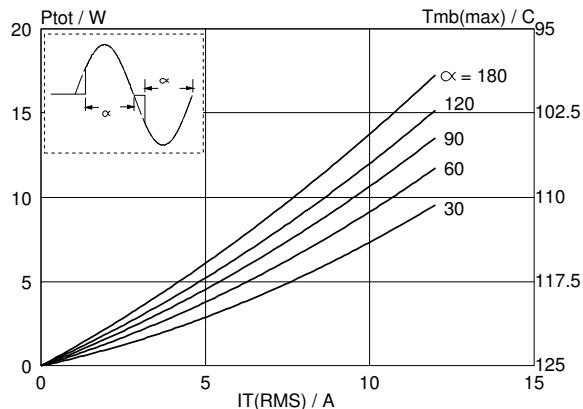


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

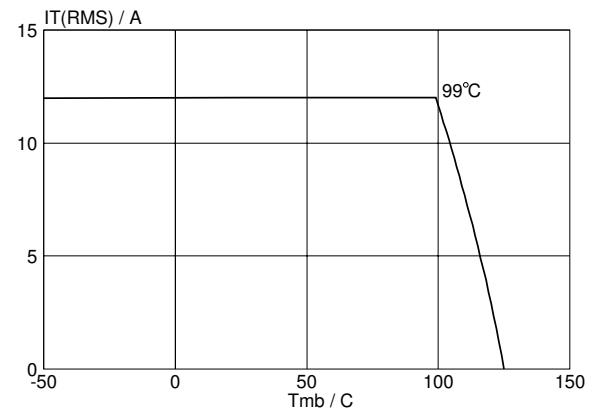


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

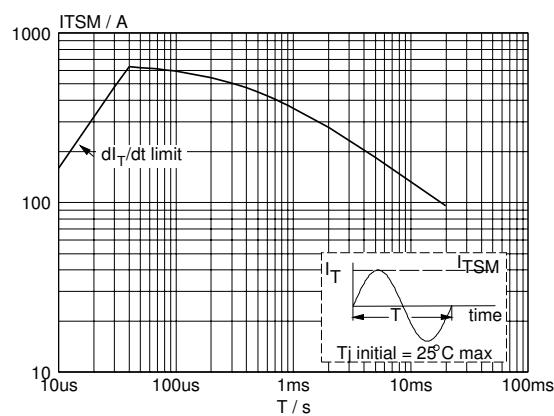


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20\text{ms}$.

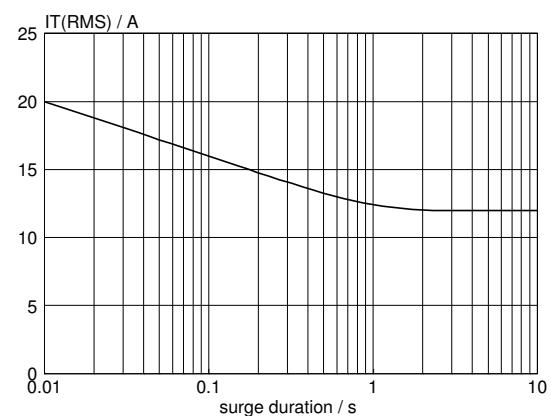


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{mb} \leq 99^\circ\text{C}$.

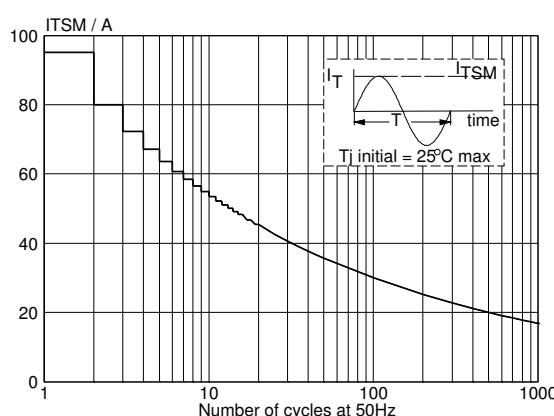


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

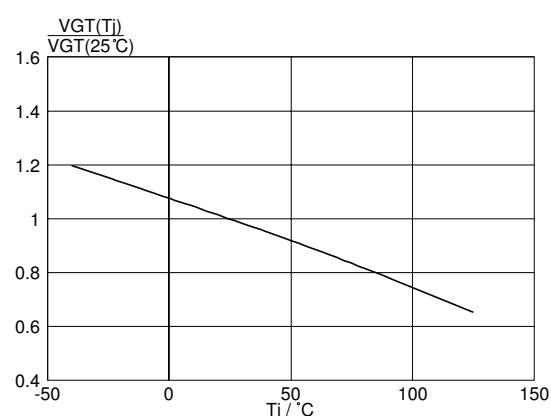


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

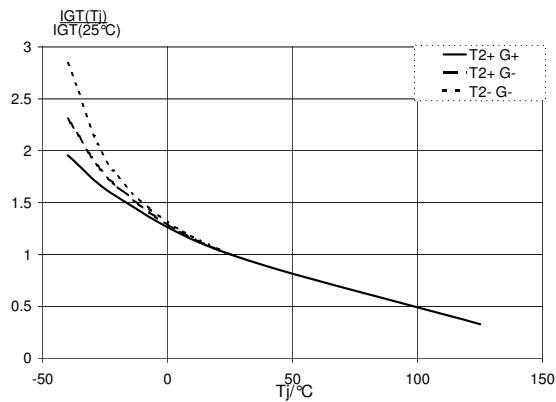


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

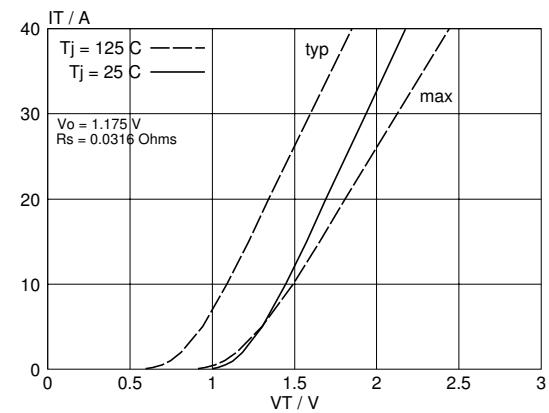


Fig.10. Typical and maximum on-state characteristic.

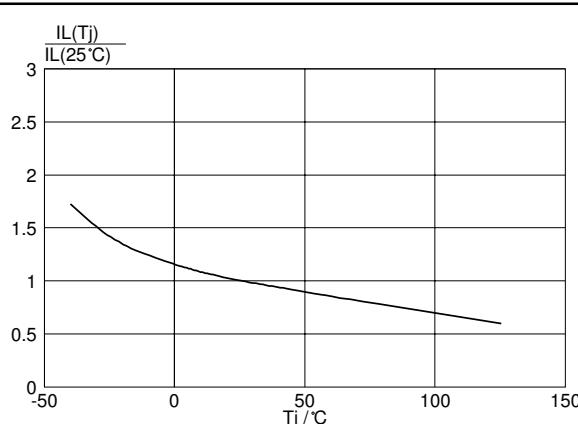


Fig.8. Normalised latching current $I_L(T_j)/I_L(25^\circ\text{C})$, versus junction temperature T_j .

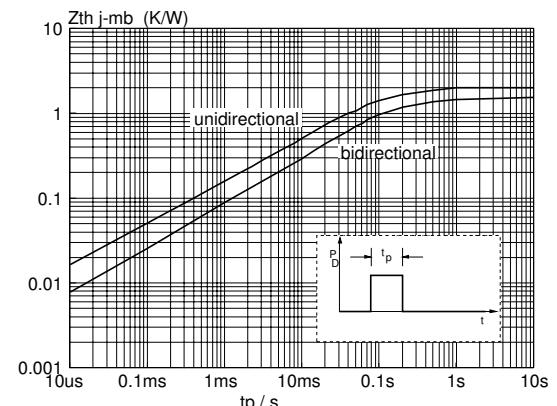


Fig.11. Transient thermal impedance $Z_{th\ j\ -mb}$, versus pulse width t_p .

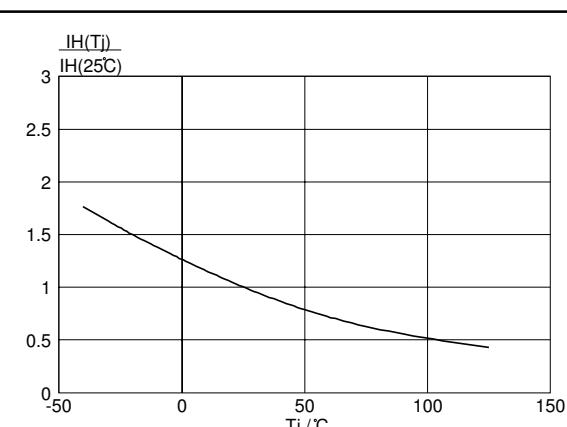


Fig.9. Normalised holding current $I_H(T_j)/I_H(25^\circ\text{C})$, versus junction temperature T_j .

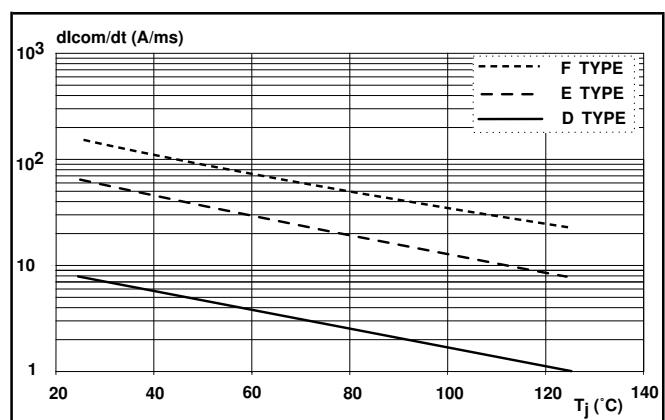
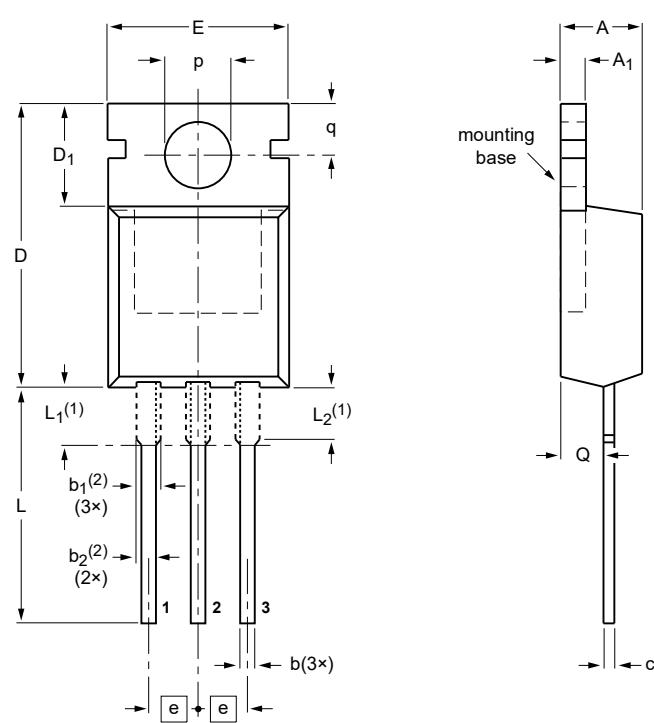


Fig.12. Minimum critical rate of change of commutating current dl_{com}/dt versus junction temperature, $dV_{com}/dt = 10\text{V}/\mu\text{s}$.

MECHANICAL DATA

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



0 5 10 mm
scale

DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁ ⁽²⁾	b ₂ ⁽²⁾	c	D	D ₁	E	e	L	L ₁ ⁽¹⁾	L ₂ ⁽¹⁾ max.	p	q	Q
mm	4.7	1.40	0.9	1.6	1.3	0.7	16.0	6.6	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.25	0.6	1.0	1.0	0.4	15.2	5.9	9.7		12.8	2.79	3.0	3.5	2.7	2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13